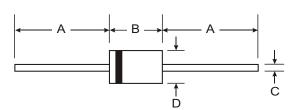




## 3.0A ULTRA-FAST GLASS PASSIVATED RECTIFIER

#### **Features**

- Glass Passivated Die Construction
- Diffused Junction
- Ultra-Fast Switching for High Efficiency
- High Current Capability and Low Forward Voltage Drop
- Surge Overload Rating to 125A Peak
- Low Reverse Leakage Current
- Plastic Material: UL Flammability Classification Rating 94V-0



### **Mechanical Data**

Case: Molded Plastic

 Terminals: Plated Leads Solderable per MIL-STD-202, Method 208

Polarity: Cathode Band
Marking: Type Number
Weight: 1.1 grams (approx.)
Mounting Position: Any

#### **DO-201AD** Dim Min Max Α 25.40 В 7.20 9.50 C 1.20 1.30 D 4.80 5.30 All Dimensions in mm

# Maximum Ratings and Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	UG3001	UG3002	UG3003	UG3004	UG3005	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	200	400	600	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	140	280	420	V
Average Rectified Output Current (Note 1)	lo	3.0					Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	125					А
Forward Voltage @ I <sub>F</sub> = 3.0A	V <sub>FM</sub>	0.95 1.25		1.25	1.7	V	
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	I <sub>RM</sub>	5.0 100					μА
Reverse Recovery Time (Note 3)	t <sub>rr</sub>	50				75	ns
Typical Junction Capacitance (Note 2)	Cj	60			30	pF	
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	35				K/W	
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +150					°C

otes: 1. Valid provided that leads are maintained at ambient temperature at a distance of 9.5mm from the case.

- 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- 3. Measured with  $I_F$  = 0.5A,  $I_R$  = 1.0A,  $I_{rr}$  = 0.25A. See figure 5.



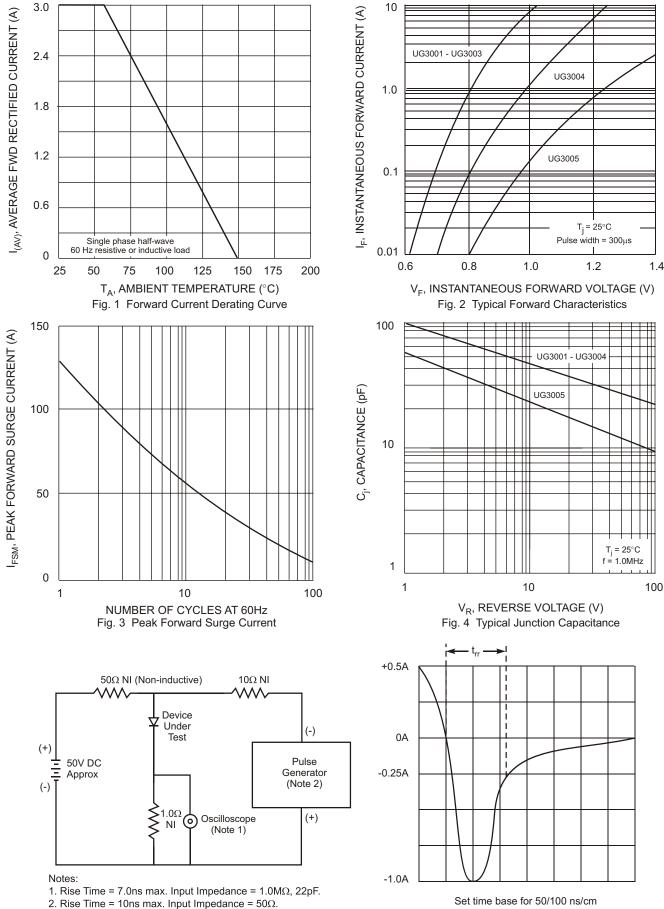


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit